

L Number	Hits	Search Text	DB	Time stamp
1	1	20020057044.did.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/02/13 15:03
2	1	20020057044.did. and base adj part	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/02/13 15:05
3	1	20020057044.did. and base	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/02/13 15:15
4	1354	((313/143) or (313/144) or (126/169E)).CCLS.	USPAT	2004/02/13 15:29
5	1354	((313/143) or (313/144) or (126/169E)).CCLS.	USPAT	2004/02/13 15:33
6	30	((313/143) or (313/144) or (126/169E)).CCLS.	US-PGPUB	2004/02/13 15:33
169	0	("landmaterialadjbond").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 16:24
170	1	20020057044.did. and material adj bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 17:24
171	1	20020057044.did. and interlayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 18:11
177	109	(klett-dittmar.in. schmittinger-simon.in. trachte-dietrich.in. benedikt-walter.in.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 19:02
234	540	(313/137).CCLS.	USPAT; US-PGPUB	2004/02/13 19:06
235	41	(123/169e).CCLS.	USPAT	2004/02/13 19:06
236	0	(123/169e).CCLS.	US-PGPUB	2004/02/13 19:06
-	98	klett-dittmar.in. schmittinger-simon.in. trachte-dietrich.in. benedikt-walter.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 19:05
-	1345	((313/143) or (313/144)).CCLS.	USPAT; US-PGPUB	2003/04/05 18:40
-	3	1485275.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:49
-	3909	(313/118-145).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:50
-	3909	(313/118-145).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:50
-	0	("1403 and spark adj plug.bi.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:50
-	1028	((313/118-145).CCLS.) and spark adj plug.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:51

-	1028	((313/118-145).CCLS.) and spark adj plug.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:44
-	1	((313/118-145).CCLS.) and spark adj plug.bi.) and shrink adj fit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 11:51
-	1	((313/118-145).CCLS.) and spark adj plug.bi.) and friction adj lock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:09
-	2	1501368.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:20
-	0	1501368.URPN.	USPAT	2003/04/07 13:20
-	3	1485275.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:29
-	0	1485275.URPN.	USPAT	2003/04/07 13:21
-	2	4870319.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:29
-	5	4870319.URPN.	USPAT	2003/04/07 13:30
-	6	("2592754"   "3295005"   "4439707"   "4476412"   "4631451"   "4695758").PN.	USPAT	2003/04/07 13:30
-	1028	((313/118-145).CCLS.) and spark adj plug.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:03
-	0	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi and housing.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 13:45
-	106	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 14:24
-	3	5731654.URPN.	USPAT	2003/04/07 13:52
-	3	5731654.URPN.	USPAT	2003/04/07 13:53
-	8	("1106703"   "1270437"   "1415668"   "1461405"   "1505373"   "1991369"   "2129576"   "5187404").PN.	USPAT	2003/04/07 13:53
-	28	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi. and (adhesive bonding epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 14:25
-	8	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi. same (adhesive bonding epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 14:27
-	0	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. same (adhesive bonding epoxy) and housing.bi. same (adhesive bonding epoxy) not ((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi. same (adhesive bonding epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 16:45

-	0	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. same (adhesive bonding epoxy) and housing.bi. same (adhesive bonding epoxy friction) not ((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi. same (adhesive bonding epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 14:28
-	0	((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. same (adhesive bonding epoxy cement) and housing.bi. same (adhesive bonding epoxy cement) not ((313/118-145).CCLS.) and spark adj plug.bi. ) and base.bi. and housing.bi. same (adhesive bonding epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 14:55
-	1	3300672.pn.	USPAT	2003/04/07 14:55
-	5	3300672.URPN.	USPAT	2003/04/07 14:55
-	1	((313/118-145).CCLS.) and cement with bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:06
-	1	((313/118-145).CCLS.) and cement with bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 17:46
-	5	((313/118-145).CCLS.) and spark adj plug.bi. and base.bi. same (weld solder) and housing.bi. same (weld solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 16:47
-	5	((313/118-145).CCLS.) and spark adj plug.bi. and base.bi. same (weld solder) and housing.bi. same (weld solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 16:55
-	2	4870319.pn. and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 16:56
-	69	((313/118-145).CCLS.) and (soldering solder welding welding) with (housing insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 17:49
-	8	((313/118-145).CCLS.) and (soldering solder welding welding) with (housing insulator) not (soldering solder welding weld) with (electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 18:00
-	0	09964829.pran.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 18:01
-	0	09964829.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 18:01
-	1	9964829.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 18:01
-	0	9964829.pran.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 18:01

-	0	9964829.prn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 18:01
-	2	1691760.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 18:23
-	3	1485275.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 18:23
-	4	(klett-dittmar.in. schmittinger-simon.in. trachte-dietrich.in. benedikt-walter.in.) and (solder soldering).bi. with (housing insulator).bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/13 19:02
-	2	1501368.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 18:26
-	3	3300672.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 18:31
-	2	1691760.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 19:01
-	38422	spark adj plug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 19:01
-	27954	spark adj plug.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 19:02
-	16	(spark adj plug.bi.) and (housing).bi. with (welding soldering solder weld).bi. and (insulator).bi. with (welding soldering solder weld).bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 19:05
-	16	(spark adj plug.bi.) and (housing).bi. with (welding soldering solder weld).bi. and (insulator).bi. with (welding soldering solder weld).bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/07 19:07
-	105	klett-dittmar.in. schmittinger-simon.in. trachte-dietrich.in. benedikt-walter.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/11 13:10
-	2	20020057044.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/11 13:10
-	1	20020057044.did.	USPAT; US-PGPUB; EPO; JPO; IBM TDB	2003/09/11 16:52

-	1	20020057044.did. and material adj bond	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 13:10
-	1	20020057044.did. and material adj bond	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 13:10
-	54	(US-4631451-\$ or US-RE35429-\$ or US-4114068-\$ or US-4893051-\$ or US-4870319-\$ or US-6337533-\$ or US-6346766-\$ or US-5731654-\$ or US-5563468-\$ or US-4490122-\$ or US-6340015-\$ or US-5983855-\$ or US-5952770-\$ or US-4746834-\$ or US-4725002-\$ or US-6373173-\$ or US-6380664-\$ or US-6509676-\$ or US-6262522-\$ or US-6274971-\$ or US-6191525-\$ or US-6215233-\$ or US-6121719-\$ or US-6097136-\$ or US-5918571-\$ or US-5239225-\$).did. or (US-5347193-\$ or US-5091672-\$ or US-5109178-\$ or US-5109817-\$ or US-4972812-\$ or US-4810929-\$ or US-4540912-\$ or US-4442375-\$ or US-4402036-\$ or US-4267483-\$ or US-5877584-\$ or US-5866973-\$ or US-5565730-\$ or US-5633557-\$).did. or (US-20020079801-\$ or US-20010030495-\$ or US-20020024160-\$ or US-20020041138-\$ or US-20020163286-\$).did. or (DE-3726714-\$ or DE-10047498-\$ or DE-10047499-\$ or EP-1267461-\$ or WO-9811637-\$ or DE-3616640-\$ or DE-3616667-\$ or WO-9300731-\$ or EP-73939-\$).did.	USPAT; US-PGPUB; EPO	2003/09/11 13:32
-	94	(US-0679041-\$ or US-3346760-\$ or US-3365605-\$ or US-3256457-\$ or US-3300672-\$ or US-2933552-\$ or US-2924642-\$ or US-2831993-\$ or US-2680432-\$ or US-2717589-\$ or US-2589338-\$ or US-2591718-\$ or US-2597794-\$ or US-2632431-\$ or US-2489410-\$ or US-2516754-\$ or US-2576469-\$ or US-2469211-\$ or US-2473317-\$ or US-2416107-\$ or US-2442858-\$ or US-2359421-\$ or US-2367840-\$ or US-2350731-\$ or US-2312103-\$ or US-2301573-\$).did. or (US-2301686-\$ or US-2309236-\$ or US-2174913-\$ or US-2136052-\$ or US-2110652-\$ or US-2083283-\$ or US-2012699-\$ or US-2049130-\$ or US-2028896-\$ or US-1997902-\$ or US-1862981-\$ or US-1723706-\$ or US-1691760-\$ or US-1685059-\$ or US-1615289-\$ or US-1648449-\$ or US-1667960-\$ or US-1552352-\$ or US-1550172-\$ or US-1555718-\$ or US-1500161-\$ or US-1502768-\$ or US-1501021-\$ or US-1501368-\$ or US-1503182-\$ or US-1483395-\$ or US-1485275-\$).did. or (US-1424526-\$ or US-1389152-\$ or US-1384818-\$ or US-1380399-\$ or US-1363843-\$ or US-1363904-\$ or US-1356129-\$ or US-1354361-\$ or US-1343348-\$ or US-1312338-\$ or US-1306834-\$ or US-1307088-\$ or US-1299040-\$ or US-1283572-\$ or US-1279974-\$ or US-1292661-\$ or US-1287570-\$ or US-1286074-\$ or US-1260884-\$ or US-1254449-\$ or US-1247049-\$ or US-1232303-\$ or US-1241561-\$ or US-1230797-\$ or US-1242367-\$ or US-1237265-\$ or US-1214471-\$).did. or (US-1200663-\$ or US-1605976-\$ or US-1178424-\$ or US-1180799-\$ or US-1155515-\$ or US-1174157-\$ or US-1126407-\$ or US-1119302-\$ or US-1100650-\$ or US-1082401-\$ or US-0981752-\$ or US-0989905-\$ or US-0994673-\$ or US-0766166-\$).did.	USOCR	2003/09/11 13:32

-	4	((US-4631451-\$ or US-RE35429-\$ or US-4114068-\$ or US-4893051-\$ or US-4870319-\$ or US-6337533-\$ or US-6346766-\$ or US-5731654-\$ or US-5563468-\$ or US-4490122-\$ or US-6340015-\$ or US-5983855-\$ or US-5952770-\$ or US-4746834-\$ or US-4725002-\$ or US-6373173-\$ or US-6380664-\$ or US-6509676-\$ or US-6262522-\$ or US-6274971-\$ or US-6191525-\$ or US-6215233-\$ or US-6121719-\$ or US-6097136-\$ or US-5918571-\$ or US-5239225-\$).did. or (US-5347193-\$ or US-5091672-\$ or US-5109178-\$ or US-5109817-\$ or US-4972812-\$ or US-4810929-\$ or US-4540912-\$ or US-4442375-\$ or US-4402036-\$ or US-4267483-\$ or US-5877584-\$ or US-5866973-\$ or US-5565730-\$ or US-5633557-\$).did. or (US-20020079801-\$ or US-20010030495-\$ or US-20020024160-\$ or US-20020041138-\$ or US-20020163286-\$).did. or (DE-3726714-\$ or DE-10047498-\$ or DE-10047499-\$ or EP-1267461-\$ or WO-9811637-\$ or DE-3616640-\$ or DE-3616667-\$ or WO-9300731-\$ or EP-73939-\$).did.) and (weld\$5 solder\$5) with bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:29
-	0	("sparkadjplug.ti.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:30
-	6135	spark adj plug.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:25
-	0	(spark adj plug.ti.) and frictional adj bond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:43
-	5	(spark adj plug.ti.) and friction\$5 near4 bond\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:31
-	10	friction\$5 near3 bond\$5 and spark adj plug.bi.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:32
-	10	(friction\$5 near3 bond\$5 and spark adj plug.bi.) and friction\$5 near3 bond\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:32
-	0	((spark adj plug.ti.) and frictional adj bond) and (material adj bond cement adhesive weld\$5 solder\$5) same (housing insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:44
-	0	((spark adj plug.ti.) and frictional adj bond) and (material adj bond cement adhesive weld\$5 solder\$5) same (housing insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:44
-	409	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5) same (housing insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:45

-	100	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5) with (insulator) with (housing shell)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:48
-	48	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5) with (insulator) with (housing shell) not with ground adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:49
-	42	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5) with (insulator) with (housing shell) not with (earth ground) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:51
-	17	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5) with (insulator) with (housing shell) not with (center earth ground) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:01
-	17	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:47
-	0	20020079801.did. and housing.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:37
-	2	20020079801.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:37
-	1	4489596.pn. and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:45
-	2	(4489596.pn. 4539503.pn.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:04
-	6	4539503.URPN.	USPAT	2003/09/11 15:47
-	0	(spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt glue) with (insulator) with (housing shell) not with (center earth ground) adj electrode not ((spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:50
-	4	(spark adj plug.ti.) and (material adj bond\$5 cement\$4 adhesi\$5 weld\$5 solder\$5 glass adj melt glue) with (insulator) with (housing shell) not with (center earth ground) adj electrode not ((spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:54
-	0	(spark adj plug.ti.) and (enamel) with (insulator) with (housing shell) not with (center earth ground) adj electrode not ((spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:35

-	1	4870319.pn.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 15:57
-	1	4870319.pn. and enamel	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 15:57
-	1	20020057044.did. and base adj part	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 18:01
-	1	20020057044.did. and base adj part	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 16:59
-	1	20020057044.did. and tubular adj section	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:09
-	1	20020057044.did. and insulator	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:09
-	1	20020057044.did. and interlayer	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:21
-	1	4489596.pn.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:26
-	1	4489596.pn. and cement	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:26
-	1	4539503.pn.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:26
-	1	4539503.pn. and cement	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 17:26
-	1	20020057044.did. and ceramic with treat\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 19:53
-	1	20020057044.did. and ceramic with treat\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 18:01
-	3	(4489596.pn. 4539503.pn.) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:04
-	2	(4489596.pn. 4539503.pn.) and ceramic	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 18:06
-	2	(4489596.pn. 4539503.pn.) and ceramic with (insulator dielectric)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 18:14
-	1	3300672.pn.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 18:15



-	6135	spark adj plug.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:25
-	0	(spark adj plug.ti. ) and (ceramic) near5 insulator with (roughen\$6 scratch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:42
-	0	(spark adj plug.ti. ) and (ceramic) with insulator with (roughen\$6 scratch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:25
-	2	(spark adj plug.ti.) and (epoxy) with (insulator) with (housing shell) not with (center earth ground) adj electrode not ((spark adj plug.ti.) and (material adj bond\$5 cement adhesive weld\$5 solder\$5 glass adj melt) with (insulator) with (housing shell) not with (center earth ground) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:36
-	8	("1264870"   "1433149"   "1753833"   "2174362"   "2312103"   "2499823"   "3087747"   "3451110").PN.	USPAT	2003/09/11 18:38
-	0	(spark adj plug.ti. ) and (ceramic) near5 insulator with (sanded roughen\$6 scratch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:42
-	2	(spark adj plug.ti. ) and (ceramic) near5 insulator with (sand\$5 rough\$9 scratch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:43
-	2	(spark adj plug.ti. ) and (ceramic) near5 insulator with (sand\$5 rough\$9 scratch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:46
-	2	(spark adj plug.ti. ) and insulator with fired near3 aluminum adj oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:47
-	2	(spark adj plug.ti. ) and fired near3 aluminum adj oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:47
-	2	(spark adj plug.ti. ) and fired with aluminum adj oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:47
-	1	(spark adj plug.ti. ) and rough\$5 with aluminum adj oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:47
-	1	(spark adj plug.ti. ) and rough\$5 same aluminum adj oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:49
-	6	(spark adj plug.ti. ) and rough\$5 near3 (ceramic insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:59

-	1	(spark adj plug.ti. ) and undulat\$5 near3 (ceramic insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:58
-	0	(spark adj plug.ti. ) and sand5 near3 (ceramic insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:58
-	3	(spark adj plug.ti. ) and sand\$5 near3 (ceramic insulator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:58
-	0	4870319.pn. and bond\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 18:59
-	1	20020057044.did. and material near3 bond\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 20:35
-	3	(spark adj plug.ti. ) and cement with bond\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 20:11
-	3	(spark adj plug.ti. ) and cement same bond\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 20:11
-	1	20020057044.did. and connect\$5	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/09/11 20:36
-	40	(123/169e).CCLS.	USPAT; US-PGPUB	2003/09/11 20:55
-	5	((123/169e).CCLS.) and (glue cement weld\$4 solder\$4 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 20:57
-	1368	((313/143) or (313/144)).CCLS.	USPAT; US-PGPUB	2003/09/11 20:57
-	0	("20020057044.did. ").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/02/13 14:19
-	2	20020057044.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/13 14:20